

Special Issue on Micro/Nanomachining of Composites

CALL FOR PAPERS

Composite materials have attracted more and more interests for different industrial applications due to their excellent and unique mechanical, chemical, physical, optical, and electrical properties. Those materials are commonly harder, tougher, brittle, and more resistant to corrosion and fatigue. And also, there are rapid growing demands on product miniaturization exploring the possibilities for integrating functionality, mobility, and intelligence in devices, which would lead to size and weight reduction, so as to substantially increase the convenience and value-add. Thereafter, they are attributed to poor machinability. Manufacturing and production engineers are often challenged to find ways to improve machinability without harming material performance, which are much focused on the machining process doability, accessibility, and productivity.

This special issue aims to publish original research papers on micro/nanomachining of composites, particularly on machining fundamental and material removal mechanism. Machinability cannot be simplified as a material property used for measuring machining performance, but rather considering the machining as a system affected by material microstructure, grain boundary, treatment, hardness, yield/tensile strength, Young's modulus, thermal conductivity, and so forth.

Potential topics include but are not limited to the following:

- ▶ Machining fundamental and mechanism
- ▶ Novel machining process
- ▶ Multiple-material machining
- ▶ Hybrid micro/nanomachining
- ▶ Composite machining simulation
- ▶ Process and tool condition monitoring

Authors can submit their manuscripts through the Manuscript Tracking System at <https://mts.hindawi.com/submit/journals/amse/mnma/>.

Papers are published upon acceptance, regardless of the Special Issue publication date.

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